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Tflex 700

Thermal Gap Filler

PRODUCT DESCRIPTION

Tflex™ 700 is a 5 W/mK soft gap filler thermal interface material with great thermal performance and high compliancy. The soft interface pad conforms to component topography, resulting in little or no stress on the components and mating chassis or parts.

Unique silicone and ceramic filler technology allows a combination of high compliancy and high thermal performance. Tflex™ 700 is stable from -40°C thru 200°C and meets UL 94V0 flame rating. Naturally tacky, it requires no additional adhesive coating which inhibits thermal performance.

FEATURES AND BENEFITS

- Thermal conductivity 5.0 W/mK
- Highly compliant
- Low thermal resistance even at low pressure
- Available in thicknesses from 0.5mm thru 5.0mm (0.020” thru 0.200”) in 0.25mm (0.010”) increments
- Naturally tacky for adhesion during assembly and transport

TYPICAL PROPERTIES

PROPERTY	TYPICAL VALUE	TEST METHOD
Construction	Filled Silicone Sheet	
Color	Dark Grey	Visual
Thermal Conductivity	5.0 W/mK	Hot Disk
Hardness (3 sec)	78 (<1mm) 66 (>1mm)	ASTM D2240
Specific Gravity	1.73	Helium Pycnometer
Flammability	94V0	UL 94
Operating Temperature	-40°C to 200°C	
Outgassing TML	1.0%	ASTM E595
Outgassing CVCM	0.13%	ASTM E595
Thickness Range	0.5mm - 5.0mm (0.020” - 0.200”)	

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